imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832 Email & Skype: info@chipsmall.com Web: www.chipsmall.com Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China







SPECIFICATION

- · Supplier : Samsung electro-mechanics
- · Product : Multi-layer Ceramic Capacitor
- · Samsung P/N:
- CL10B104KO8NNNC

(Reference sheet)

- · Description :
- CAP, 100nF, 16V, ±10%, X7R, 0603

A. Samsung Part Number

		<u>CL</u> ①	<u>10</u> ②	<u>B</u> 3	<u>104</u> ④	<u>K</u> 5	<mark>0</mark> 6	<u>8</u> 7	<u>N</u> 8	<u>N</u> 9	<u>N</u> 10	<mark>C</mark> 1	
1	Series	Samsung Mult	i-laye	r Cer	amic C	apac	itor						
2	Size	0603 (inch co	ode)		L:	1.60	± 0.10	mm			W:	$0.80\pm0.10 \text{ mm}$	
3	Dielectric	X7R				8	Inner	elect	trode			Ni	
4	Capacitance	100 nF					Term	inatio	on			Cu	
5	Capacitance	±10 %					Platir	ng				Sn 100% (Pb Free)	
	tolerance					9	Prod	uct				Normal	
6	Rated Voltage	16 V				10	Spec	ial				Reserved for future use	
\bigcirc	Thickness	0.80 ± 0.10 mm	ı			1	Pack	aging	I			Cardboard Type, 7" reel	

B. Structure & Dimension



Samsung D/N	Dimension(mm)							
Samsung P/N	L	W	Т	BW				
CL10B104KO8NNNC	1.60 ± 0.10	0.80 ± 0.10	0.80 ± 0.10	0.30 ± 0.20				

C. Samsung Reliablility Test and Judgement Condition

Tan δ (DF)0.035Insulation10,000ResistanceWhichAppearanceNo abrWithstandingNo dieVoltagemechaTemperatureX7RCharacteristics(From-Adhesive StrengthNo peeof TerminationterminaBending StrengthCapacSolderabilityMore theResistance toCapacSoldering HeatTan δ,Vibration TestCapac	specified tolerance max. Mohm or 100Mohm×/ ^{JF} ever is smaller formal exterior appearance ectric breakdown or nical breakdown 55°C to 125°C, Capacitance change ling shall be occur on the al electrode tance change : within ±12.5%	500g·f, for 10±1 sec. Bending to the limit (1mm)
Insulation10,000ResistanceWhichAppearanceNo abrWithstandingNo dieVoltagemechaTemperatureX7RCharacteristics(From-Adhesive StrengthNo peeof TerminationterminaBending StrengthCapacSolderabilityMore thResistance toCapacSoldering HeatTan δ,Vibration TestCapac	Mohm or 100Mohm×µ ^F ever is smaller formal exterior appearance ectric breakdown or nical breakdown 55°C to 125°C, Capacitance change ling shall be occur on the al electrode tance change : within ±12.5%	treated at 150 °C +0/-10 °C for 1 hour and maintained in ambient air for 24±2 hours. Rated Voltage 60~120 sec. Microscope (×10) 250% of the rated voltage e should be within ±15%) 500g f, for 10±1 sec. Bending to the limit (1mm)
ResistanceWhichAppearanceNo abrWithstandingNo dieVoltagemechaTemperatureX7RCharacteristics(From-Adhesive StrengthNo peeof TerminationterminaBending StrengthCapaceSolderabilityMore theResistance toCapaceSoldering HeatTan δ,Vibration TestCapace	ever is smaller formal exterior appearance ectric breakdown or nical breakdown 55°C to 125°C, Capacitance change ling shall be occur on the al electrode tance change : within ±12.5%	Microscope (×10) 250% of the rated voltage e should be within ±15%) 500g·f, for 10±1 sec. Bending to the limit (1mm)
AppearanceNo abrWithstandingNo dieWithstandingNo dieVoltagemechaTemperatureX7RCharacteristics(From-Adhesive StrengthNo peeof TerminationterminaBending StrengthCapaceSolderabilityMore theResistance toCapaceSoldering HeatTan δ,Vibration TestCapace	iormal exterior appearance ectric breakdown or nical breakdown 55℃ to 125℃, Capacitance change ling shall be occur on the al electrode tance change : within ±12.5%	250% of the rated voltage e should be within ±15%) 500g·f, for 10±1 sec. Bending to the limit (1mm)
WithstandingNo dieVoltagemechaTemperatureX7RCharacteristics(From-Adhesive StrengthNo peeringof TerminationterminaBending StrengthCapaceSolderabilityMore the is to beResistance toCapaceSoldering HeatTan δ, Vibration Test	ectric breakdown or nical breakdown 55°C to 125°C, Capacitance change ling shall be occur on the al electrode tance change : within ±12.5%	250% of the rated voltage e should be within ±15%) 500g·f, for 10±1 sec. Bending to the limit (1mm)
Voltage mecha Temperature X7R Characteristics (From- Adhesive Strength No peedotic of Termination termination Bending Strength Capacitie Solderability More the strength is to be strength Resistance to Capacitie Soldering Heat Tan δ, Vibration Test	nical breakdown 55°C to 125°C, Capacitance change ling shall be occur on the al electrode tance change : within ±12.5%	e should be within ±15%) 500g·f, for 10±1 sec. Bending to the limit (1mm)
TemperatureX7RCharacteristics(From-Adhesive StrengthNo peerof TerminationterminationBending StrengthCapaceSolderabilityMore the is to beerResistance toCapaceSoldering HeatTan δ, Capace	$55 \degree to 125 \degree$, Capacitance change ling shall be occur on the al electrode tance change : within ±12.5%	500g·f, for 10±1 sec. Bending to the limit (1mm)
Characteristics(From-Adhesive StrengthNo peedof TerminationterminationBending StrengthCapacitySolderabilityMore the is to beedResistance toCapacitySoldering HeatTan δ, Capacity	ling shall be occur on the al electrode tance change : within ±12.5%	500g·f, for 10±1 sec. Bending to the limit (1mm)
Adhesive Strength of Termination No peet termination Bending Strength Capac Solderability More the is to be Resistance to Capac Soldering Heat Tan δ, Vibration Test Capac	ling shall be occur on the al electrode tance change : within ±12.5%	500g·f, for 10±1 sec. Bending to the limit (1mm)
of TerminationterminationBending StrengthCapaciSolderabilityMore the state of the	al electrode tance change : within ±12.5%	Bending to the limit (1mm)
Bending Strength Capac Solderability More the state of the state	tance change : within ±12.5%	
Solderability More the second se		
is to be Resistance to Capac Soldering Heat Τan δ, Vibration Test Capac	nan 75% of terminal surface	
is to be Resistance to Capac Soldering Heat Τan δ, Vibration Test Capac	nan 75% of terminal surface	with 1.0mm/sec.
Resistance toCapacitiesSoldering HeatΤan δ,Vibration TestCapacities		SnAg3.0Cu0.5 solder
Soldering HeatTan δ,Vibration TestCapac	soldered newly	245±5℃, 3±0.3sec.
Soldering HeatTan δ,Vibration TestCapac		(preheating : 80~120°C for 10~30sec.)
Vibration Test Capac	tance change : within ±7.5%	Solder pot : 270±5°C, 10±1sec.
	IR : initial spec.	
	tance change : within ± 5% IR : initial spec.	Amplitude : 1.5mm From 10Hz to 55Hz (return : 1min.) 2hours × 3 direction (x, y, z)
Moisture Capac	tance change : within ±12.5%	With rated voltage
Resistance Tan ō	0.05 max	40±2℃, 90~95%RH, 500+12/-0hrs
IR :	500Mohm or 25Mohm × μ F	
	Whichever is smaller	
High Temperature Capac	tance change : within ±12.5%	With 200% of the rated voltage
	0.05 max	Max. operating temperature
IR :	1,000Mohm or 50Mohm × μ F Whichever is smaller	1000+48/-0hrs
Temperature Capaci	tance change : within ±7.5%	1 cycle condition
-	IR : initial spec.	Min. operating temperature $\rightarrow 25^{\circ}C$
	·	\rightarrow Max. operating temperature \rightarrow 25°C

X The reliability test condition can be replaced by the corresponding accelerated test condition.

D. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5°C, 10sec. Max)

Product specifications included in the specifications are effective as of March 1, 2013. Please be advised that they are standard product specifications for reference only. We may change, modify or discontinue the product specifications without notice at any time. So, you need to approve the product specifications before placing an order. Should you have any question regarding the product specifications,

please contact our sales personnel or application engineers.

- Disclaimer & Limitation of Use and Application -

The products listed in this Specification sheet are **NOT** designed and manufactured for any use and applications set forth below.

Please note that any misuse of the products deviating from products specifications or information provided in this Spec sheet may cause serious property damages or personal injury. We will **NOT** be liable for any damages resulting from any misuse of the products, specifically including using the products for high reliability applications as listed below.

If you have any questions regarding this 'Limitation of Use and Application', you should first contact our sales personnel or application engineers.

- Aerospace/Aviation equipment
- 2 Automotive or Transportation equipment (vehicles, trains, ships, etc)
- 3 Medical equipment
- ④ Military equipment
- *⑤* Disaster prevention/crime prevention equipment
- *ⓐ* Any other applications with the same as or similar complexity or reliability to the applications set forth above.